



### Description

The 1210L series device provides surface mount overcurrent protection for applications where space is at a premium and resettable protection is desired.

### Features

- RoHS compliant and lead-free
- Fast response to fault currents
- Compact design saves board space
- Low resistance
- Low-profile
- Compatible with high temperature solders

### Applications

- USB peripherals
- Disk drives
- CD-ROMs
- PC motherboards - plug and play protection
- Mobile phones - battery and port protection
- PDAs / digital cameras
- Game console port protection

### Agency Approvals

AGENCY AGENCY FILE NUMBER



E183209



R50082521

### Electrical Characteristics

Part Number	Marking	I <sub>hold</sub> (A)	I <sub>trip</sub> (A)	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	P <sub>d max.</sub> (W)	Maximum Time To Trip		Resistance			Agency Approvals	
							Current (A)	Time (Sec.)	R <sub>min</sub> (Ω)	R <sub>typ</sub> (Ω)	R <sub>1max</sub> (Ω)		
1210L005	A	0.05	0.15	30	10	0.60	0.25	1.50	3.600	25.00	50.00	X	X
1210L010	B	0.10	0.30	30	10	0.60	0.50	1.50	1.600	7.000	15.00	X	X
1210L020	C	0.20	0.40	30	10	0.60	8.00	0.02	0.800	2.900	5.000	X	X
1210L035	E	0.35	0.70	6	100	0.60	8.00	0.20	0.320	0.810	1.300	X	X
1210L050	F	0.50	1.00	13.2	100	0.60	8.00	0.10	0.250	0.550	0.900	X	X
1210L075	G	0.75	1.50	6	100	0.60	8.00	0.10	0.130	0.290	0.400	X	X
1210L110	H	1.10	2.20	6	100	0.60	8.00	0.30	0.060	0.140	0.210	X	X
1210L150	K	1.50	3.00	6	100	0.80	8.00	0.50	0.040	0.070	0.110	X	X

I<sub>hold</sub> = Hold current: maximum current device will pass without tripping in 20°C still air.

I<sub>trip</sub> = Trip current: minimum current at which the device will trip in 20°C still air.

V<sub>max</sub> = Maximum voltage device can withstand without damage at rated current (I<sub>max</sub>)

I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>)

P<sub>d</sub> = Power dissipated from device when in the tripped state at 20°C still air.

R<sub>min</sub> = Minimum resistance of device in initial (un-soldered) state.

R<sub>typ</sub> = Typical resistance of device in initial (un-soldered) state.

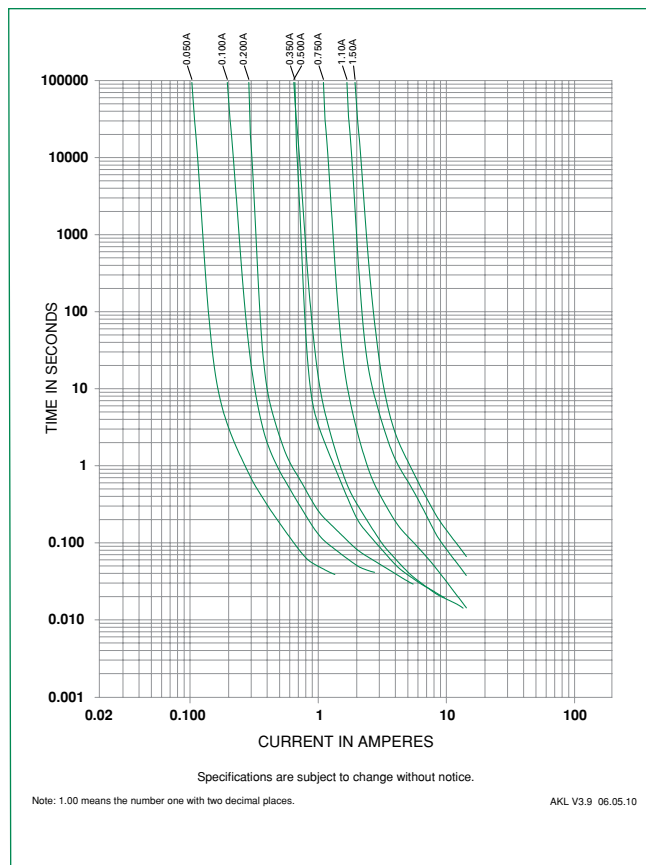
R<sub>1max</sub> = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

**Caution:** Operation beyond the specified rating may result in damage and possible arcing and flame.

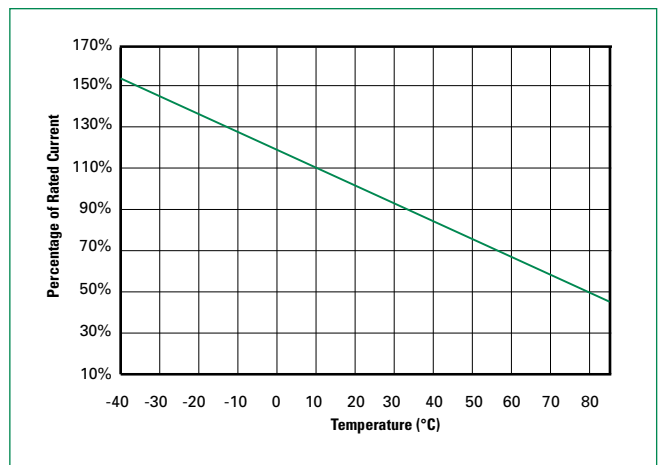
### Temperature Derating

Part Number	Ambient Operation Temperature								
	-40°C	-20°C	0°C	23°C	40°C	50°C	60°C	70°C	85°C
1210L005	0.08	0.07	0.06	0.05	0.04	0.04	0.03	0.03	0.02
1210L010	0.16	0.14	0.12	0.10	0.08	0.07	0.06	0.05	0.03
1210L020	0.29	0.26	0.22	0.20	0.16	0.14	0.13	0.11	0.08
1210L035	0.47	0.45	0.40	0.35	0.33	0.28	0.24	0.21	0.18
1210L050	0.76	0.67	0.58	0.50	0.43	0.40	0.36	0.32	0.28
1210L075	1.00	0.97	0.86	0.75	0.64	0.59	0.54	0.48	0.40
1210L110	1.69	1.48	1.29	1.10	0.88	0.76	0.65	0.57	0.43
1210L150	2.13	1.92	1.71	1.50	1.26	1.14	1.01	0.89	0.71

### Average Time Current Curves



### Temperature Derating Curve



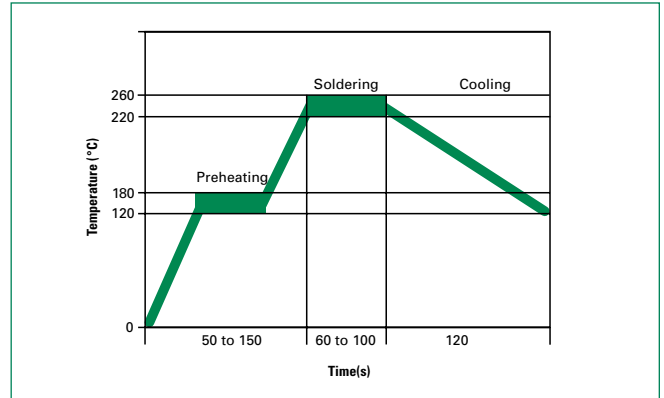
The average time current curves and temperature derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

**Soldering Parameters**

Condition	Reflow
Peak Temp/ Duration Time	260°C / 10 Sec
Time above liquids (TAL) 220°C	60 Sec ~ 100 Sec
Preheat 120°C~ 180°C	50 Sec ~ 150 Sec
Storage Condition	0°C~35°C, ≤70%RH

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N<sub>2</sub> environment for lead-free
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Devices can be cleaned using standard industry methods and solvents.

**Note:** If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.


**Physical Specifications**

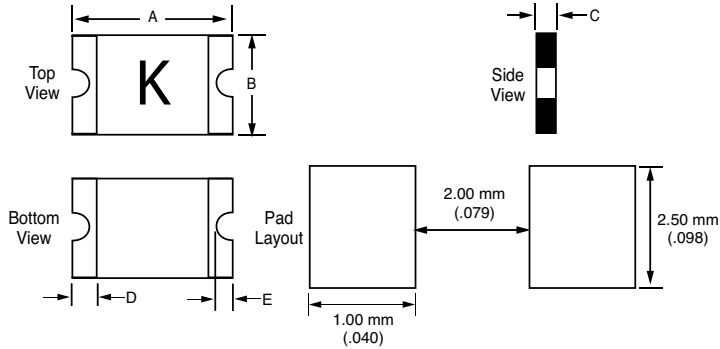
Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.

**Environmental Specifications**

Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours ±5% typical resistance change
Humidity Aging	+85°C, 85% R.H. 1000 hours ±5% typical resistance change
Thermal Shock	MIL-STD-202 Method 107G +85°C/-40°C 20 times -30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A No change

### Dimensions

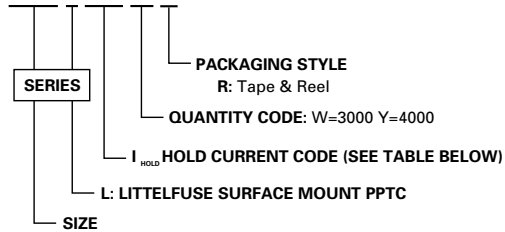
MARKING CODE VARIES WITH AMPERAGE RATING (SEE CHART)  
SHOWN IS 1.5AMP RATING



Part Number	A				B				C				D		E			
	Inches		mm		Inches		mm		Inches		mm		Inches	mm	Inches	mm	Inches	mm
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	Min.	Max.	Min.	Max.
1210L005	0.12	0.14	3.00	3.43	0.09	0.11	2.35	2.80	0.03	0.05	0.75	1.25	0.01	0.25	0.008	0.02	0.20	0.50
1210L010	0.12	0.14	3.00	3.43	0.09	0.11	2.35	2.80	0.03	0.05	0.75	1.25	0.01	0.25	0.008	0.02	0.20	0.50
1210L020	0.12	0.14	3.00	3.43	0.09	0.11	2.35	2.80	0.02	0.04	0.60	1.00	0.01	0.25	0.008	0.02	0.20	0.50
1210L035	0.12	0.14	3.00	3.43	0.09	0.11	2.35	2.80	0.02	0.03	0.50	0.85	0.01	0.25	0.008	0.02	0.20	0.50
1210L050	0.12	0.14	3.00	3.43	0.09	0.11	2.35	2.80	0.02	0.03	0.50	0.85	0.01	0.25	0.008	0.02	0.20	0.50
1210L075	0.12	0.14	3.00	3.43	0.09	0.11	2.35	2.80	0.02	0.03	0.50	0.85	0.01	0.25	0.008	0.02	0.20	0.50
1210L110	0.12	0.14	3.00	3.43	0.09	0.11	2.35	2.80	0.04	0.05	0.90	1.30	0.01	0.25	0.008	0.02	0.20	0.50
1210L150	0.12	0.14	3.00	3.43	0.09	0.11	2.35	2.80	0.03	0.07	0.80	1.80	0.01	0.25	0.008	0.02	0.20	0.50

### Part Numbering System

**1210 L 110 W R**



### Packaging

$I_{hold}$ (A)	$I_{hold}$ Code	Packaging Option	Quantity	Quantity & Packaging Codes
0.05	005	Tape and Reel	3000	WR
0.10	010	Tape and Reel	3000	WR
0.20	020	Tape and Reel	3000	WR
0.35	035	Tape and Reel	4000	YR
0.50	050	Tape and Reel	4000	YR
0.75	075	Tape and Reel	4000	YR
1.10	110	Tape and Reel	3000	WR
1.50	150	Tape and Reel	2000	PR